

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	§	
Ling Chen et al.	§	
	§	Group Art Unit: 2823
Serial No.: 10/741,824	§	
	§	
Confirmation No.: 2621	§	
	§	Examiner: John M. Parker
Filed: April 21, 2006	§	
	§	
For: Enhancement of CU Line	§	
Reliability Using Thin ALD	§	
Tan Film to Cap the CU	§	
Line	§	

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

RESPONSE TO OFFICE ACTION DATED APRIL 21, 2006

In response to the Office Action dated April 21, 2006, having a shortened statutory period for response set to expire on July 21, 2006, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicant believes that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/APPM/007532/KMT for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper. **Remarks** begin on page 7 of this paper.